

**HIGH VOLTAGE ULTRAFAST RECTIFIER**
**MAIN PRODUCT CHARACTERISTICS**

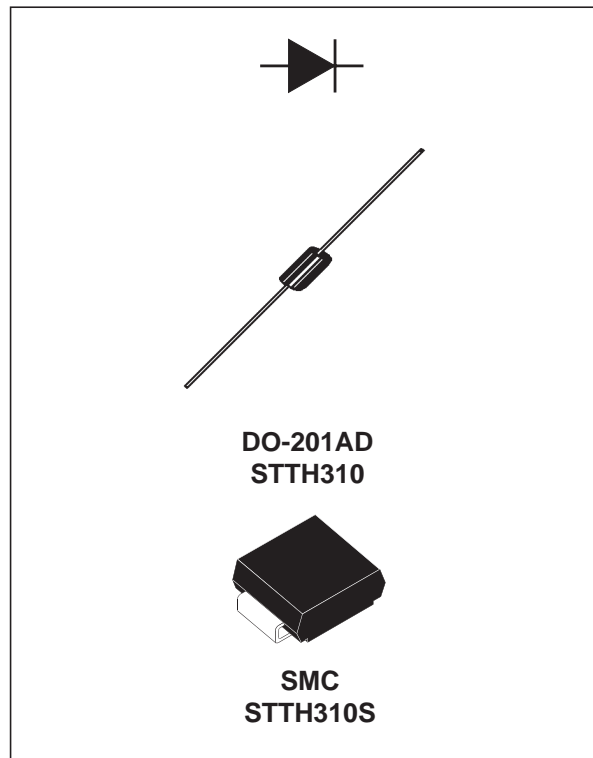
<b>I<sub>F(AV)</sub></b>	<b>3 A</b>
<b>V<sub>RRM</sub></b>	<b>1000 V</b>
<b>T<sub>j (max)</sub></b>	<b>175 °C</b>
<b>V<sub>F (max)</sub></b>	<b>1.42 V</b>

**FEATURES AND BENEFITS**

- Low forward voltage drop
- High reliability
- High surge current capability
- Soft switching for reduced EMI disturbances
- Planar technology

**DESCRIPTION**

The STTH310, which is using ST ultrafast high voltage planar technology, is specially suited for free-wheeling, clamping, snubbing, demagnetization in power supplies and other power switching applications.


**ABSOLUTE RATINGS (limiting values)**

Symbol	Parameter		Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage		1000	V	
V <sub>(RMS)</sub>	RMS voltage		700	V	
I <sub>F(AV)</sub>	Average forward current	TI = 75°C δ = 0.5	DO-201AD	3	A
		TI = 75°C δ = 0.5	SMC	3	
I <sub>FSM</sub>	Forward surge current t = 8.3 ms		DO-201AD	55	A
			SMC	45	
T <sub>stg</sub>	Storage temperature range		- 50 + 175	°C	
T <sub>j</sub>	Maximum operating junction temperature		+ 175	°C	

## THERMAL PARAMETERS

Symbol	Parameter			Value	Unit
$R_{th(j-l)}$	Junction to lead	L = 10 mm	DO-201AD	20	°C/W
			SMC	20	
$R_{th(j-a)}$	Junction to ambient	L = 10 mm	DO-201AD	75	

## STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R$	Reverse leakage current	$V_R = 1000V$	$T_j = 25^\circ C$			10	$\mu A$
			$T_j = 125^\circ C$			50	
$V_F$	Forward voltage drop	$I_F = 3 A$	$T_j = 25^\circ C$			1.7	V
			$T_j = 150^\circ C$		0.98	1.42	

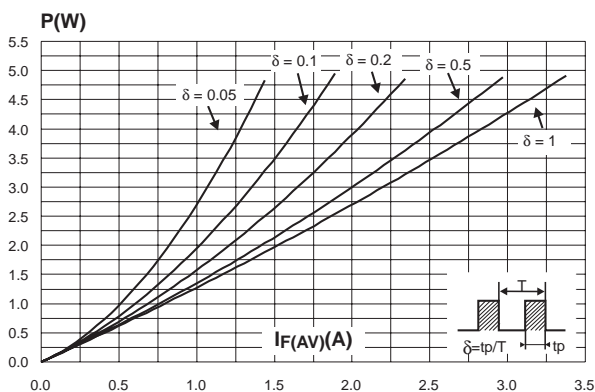
To evaluate the maximum conduction losses use the following equation :

$$P = 1.20 \times I_{F(AV)} + 0.075 \times I_{F(RMS)}^2$$

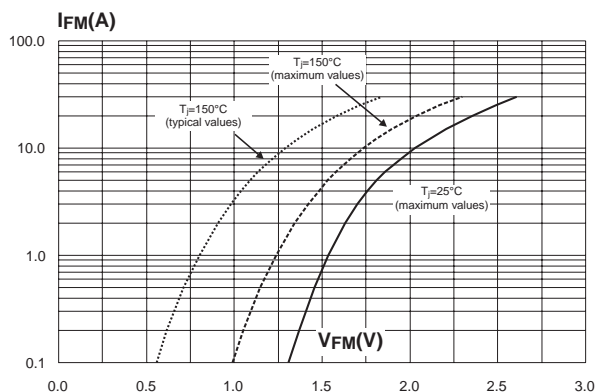
## DYNAMIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 0.5 A$ $I_{rr} = 0.25 A$ $I_R = 1A$	$T_j = 25^\circ C$			75	ns
$t_{fr}$	Forward recovery time	$I_F = 3 A$ $dI_F/dt = 50 A/\mu s$ $V_{FR} = 1.1 \times V_F \text{ max}$	$T_j = 25^\circ C$			300	ns
$V_{FP}$	Forward recovery voltage						12

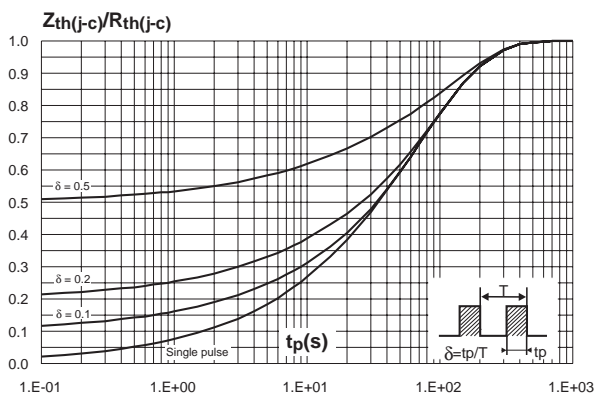
**Fig. 1:** Conduction losses versus average current.



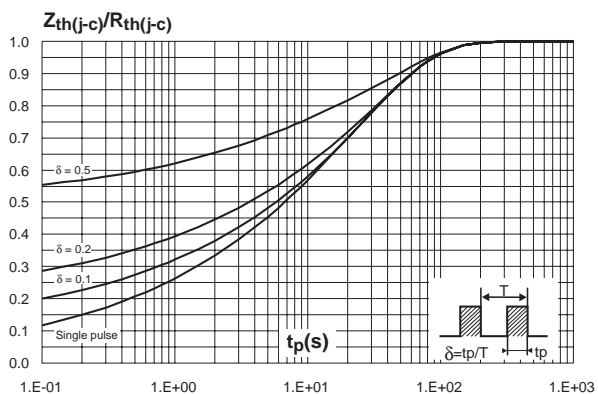
**Fig. 2:** Forward voltage drop versus forward current.



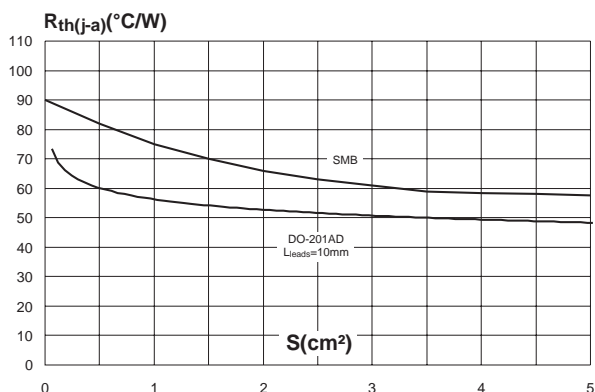
**Fig. 3-1:** Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4,  $L_{leads} = 10\text{mm}$ ) (DO-201AD).



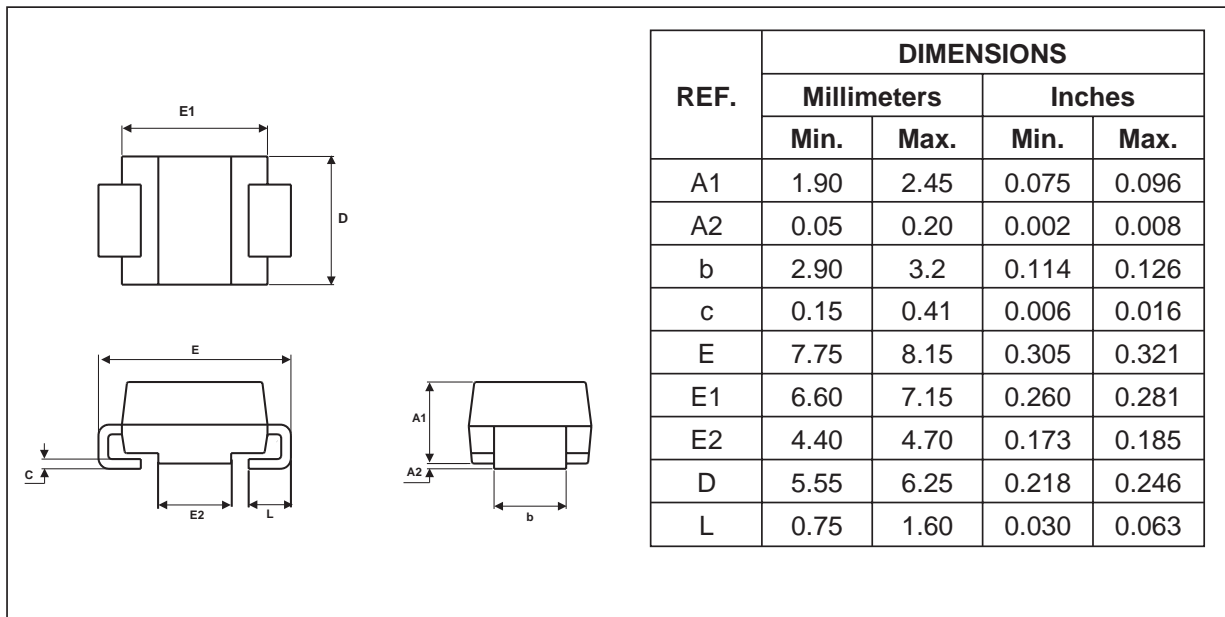
**Fig. 3-2:** Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4,  $S=1\text{cm}^2$ ) (SMC).



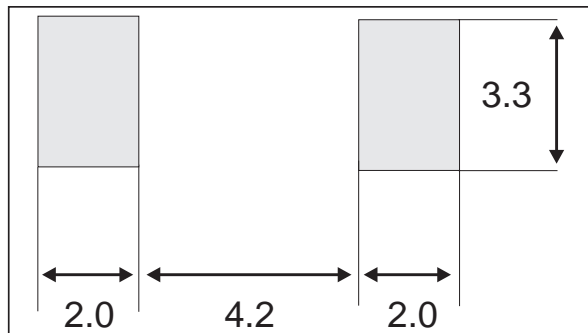
**Fig. 4:** Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed circuit board FR4, copper thickness:  $35\mu\text{m}$ ).

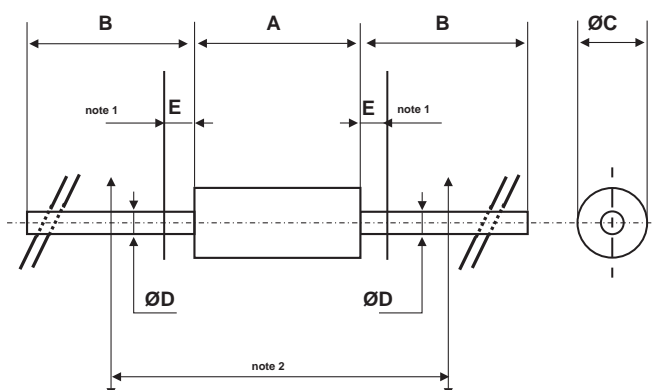


PACKAGE MECHANICAL DATA  
SMC



FOOTPRINT (in millimeters)



**PACKAGE MECHANICAL DATA**  
 DO-201AD


REF.	DIMENSIONS				NOTES
	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
A		9.50		0.374	1 - The lead diameter $\varnothing D$ is not controlled over zone E 2 - The minimum length which must stay straight between the right angles after bending is 0.59"(15 mm)
B	25.40		1.000		
C		5.30		0.209	
D		1.30		0.051	
E		1.25		0.049	

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
STTH310	STTH310	DO-201AD	1.12 g	600	Ammopack
STTH310S	S10	SMC	0.245 g	2500	Tape & reel
STTH310RL	STTH310	DO-201AD	1.12 g	1900	Tape & reel

- Epoxy meets UL 94,V0

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